

[*WAFER LEVEL PACKAGING AND CHIP STRUCTURE*]

Abstract of Disclosure

FILE: 8289USF.RTF19A chip structure comprises a wafer, an insulation layer, some conductive paste, a plurality of ball pads, a solder mask and a plurality of solder balls. The wafer has an active surface. The insulation layer is formed over the active surface of the wafer. The insulation layer has a plurality of open windows. The conductive paste fills the open windows. The ball pads are formed over the insulation layer in electrical connection with the conductive paste. The solder mask formed over the insulation layer. The solder mask exposes the ball pads. A solder ball is mounted to each ball pad.